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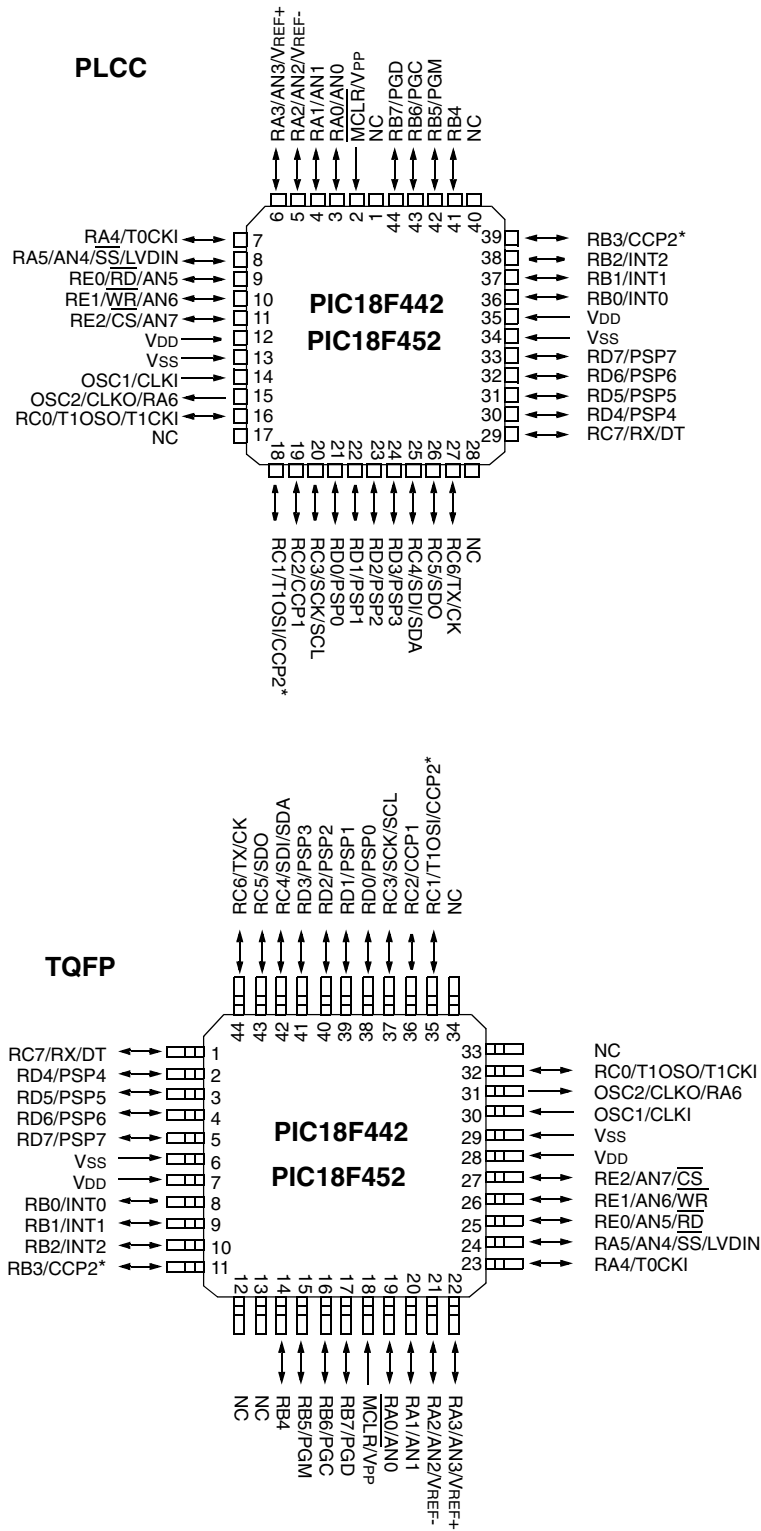
Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	23
Program Memory Size	32KB (16K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 5x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf252-i-sp

PIC18FXX2

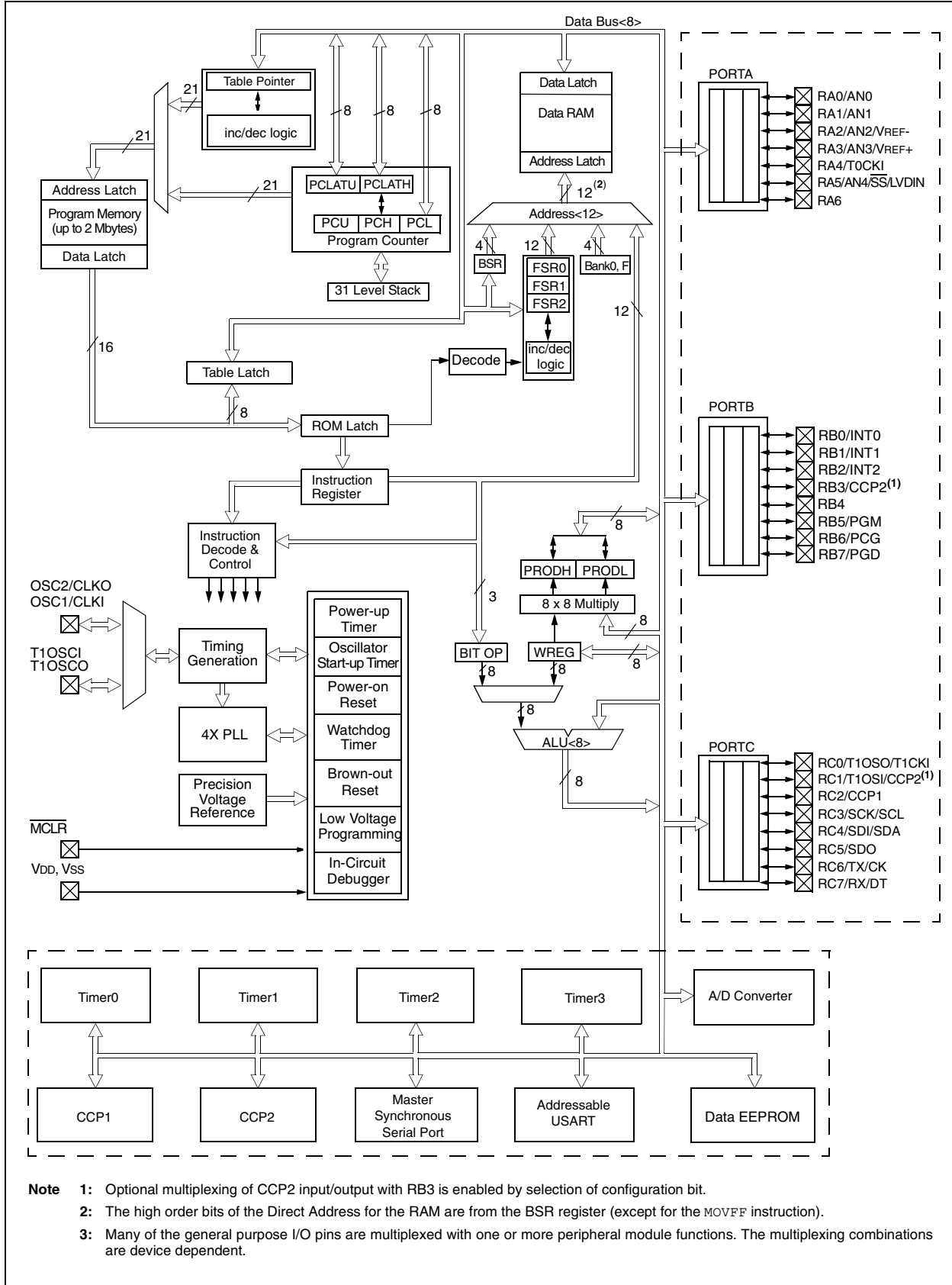
Pin Diagrams



* RB3 is the alternate pin for the CCP2 pin multiplexing.

PIC18FXX2

FIGURE 1-1: PIC18F2X2 BLOCK DIAGRAM



2.0 OSCILLATOR CONFIGURATIONS

2.1 Oscillator Types

The PIC18FXX2 can be operated in eight different Oscillator modes. The user can program three configuration bits (FOSC2, FOSC1, and FOSC0) to select one of these eight modes:

1. LP Low Power Crystal
2. XT Crystal/Resonator
3. HS High Speed Crystal/Resonator
4. HS + PLL High Speed Crystal/Resonator with PLL enabled
5. RC External Resistor/Capacitor
6. RCIO External Resistor/Capacitor with I/O pin enabled
7. EC External Clock
8. ECIO External Clock with I/O pin enabled

2.2 Crystal Oscillator/Ceramic Resonators

In XT, LP, HS or HS+PLL Oscillator modes, a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation. Figure 2-1 shows the pin connections.

The PIC18FXX2 oscillator design requires the use of a parallel cut crystal.

Note: Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications.

FIGURE 2-1: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP CONFIGURATION)

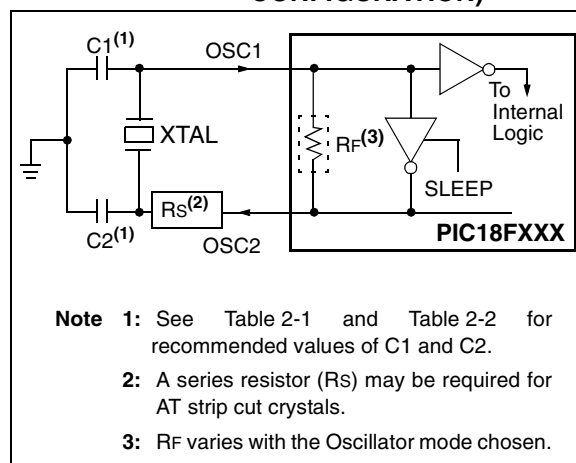


TABLE 2-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Ranges Tested:			
Mode	Freq	C1	C2
XT	455 kHz	68 - 100 pF	68 - 100 pF
	2.0 MHz	15 - 68 pF	15 - 68 pF
	4.0 MHz	15 - 68 pF	15 - 68 pF
HS	8.0 MHz	10 - 68 pF	10 - 68 pF
	16.0 MHz	10 - 22 pF	10 - 22 pF
These values are for design guidance only. See notes following this table.			
Resonators Used:			
455 kHz	Panasonic EFO-A455K04B	± 0.3%	
2.0 MHz	Murata Erie CSA2.00MG	± 0.5%	
4.0 MHz	Murata Erie CSA4.00MG	± 0.5%	
8.0 MHz	Murata Erie CSA8.00MT	± 0.5%	
16.0 MHz	Murata Erie CSA16.00MX	± 0.5%	
All resonators used did not have built-in capacitors.			

Note 1: Higher capacitance increases the stability of the oscillator, but also increases the start-up time.

2: When operating below 3V VDD, or when using certain ceramic resonators at any voltage, it may be necessary to use high-gain HS mode, try a lower frequency resonator, or switch to a crystal oscillator.

3: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components, or verify oscillator performance.

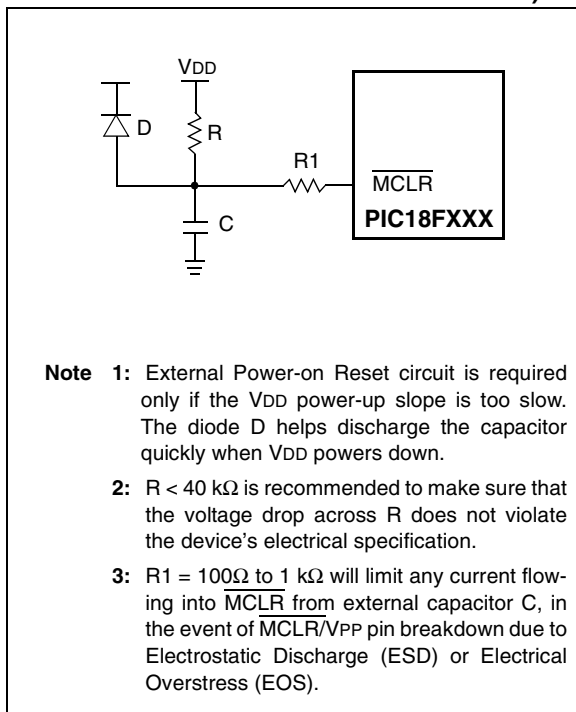
PIC18FXX2

3.1 Power-On Reset (POR)

A Power-on Reset pulse is generated on-chip when VDD rise is detected. To take advantage of the POR circuitry, just tie the $\overline{\text{MCLR}}$ pin directly (or through a resistor) to VDD. This will eliminate external RC components usually needed to create a Power-on Reset delay. A minimum rise rate for VDD is specified (parameter D004). For a slow rise time, see Figure 3-2.

When the device starts normal operation (i.e., exits the RESET condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in RESET until the operating conditions are met.

FIGURE 3-2: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



3.2 Power-up Timer (PWRT)

The Power-up Timer provides a fixed nominal time-out (parameter 33) only on power-up from the POR. The Power-up Timer operates on an internal RC oscillator. The chip is kept in RESET as long as the PWRT is active. The PWRT's time delay allows VDD to rise to an acceptable level. A configuration bit is provided to enable/disable the PWRT.

The power-up time delay will vary from chip-to-chip due to VDD, temperature and process variation. See DC parameter D033 for details.

3.3 Oscillator Start-up Timer (OST)

The Oscillator Start-up Timer (OST) provides a 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over (parameter 32). This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from SLEEP.

3.4 PLL Lock Time-out

With the PLL enabled, the time-out sequence following a Power-on Reset is different from other Oscillator modes. A portion of the Power-up Timer is used to provide a fixed time-out that is sufficient for the PLL to lock to the main oscillator frequency. This PLL lock time-out (TPLL) is typically 2 ms and follows the oscillator start-up time-out (OST).

3.5 Brown-out Reset (BOR)

A configuration bit, BOREN, can disable (if clear/programmed), or enable (if set) the Brown-out Reset circuitry. If VDD falls below parameter D005 for greater than parameter 35, the brown-out situation will reset the chip. A RESET may not occur if VDD falls below parameter D005 for less than parameter 35. The chip will remain in Brown-out Reset until VDD rises above BVDD. If the Power-up Timer is enabled, it will be invoked after VDD rises above BVDD; it then will keep the chip in RESET for an additional time delay (parameter 33). If VDD drops below BVDD while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be initialized. Once VDD rises above BVDD, the Power-up Timer will execute the additional time delay.

3.6 Time-out Sequence

On power-up, the time-out sequence is as follows: First, PWRT time-out is invoked after the POR time delay has expired. Then, OST is activated. The total time-out will vary based on oscillator configuration and the status of the PWRT. For example, in RC mode with the PWRT disabled, there will be no time-out at all. Figure 3-3, Figure 3-4, Figure 3-5, Figure 3-6 and Figure 3-7 depict time-out sequences on power-up.

Since the time-outs occur from the POR pulse, if $\overline{\text{MCLR}}$ is kept low long enough, the time-outs will expire. Bringing $\overline{\text{MCLR}}$ high will begin execution immediately (Figure 3-5). This is useful for testing purposes or to synchronize more than one PIC18FXXX device operating in parallel.

Table 3-2 shows the RESET conditions for some Special Function Registers, while Table 3-3 shows the RESET conditions for all the registers.

4.0 MEMORY ORGANIZATION

There are three memory blocks in Enhanced MCU devices. These memory blocks are:

- Program Memory
- Data RAM
- Data EEPROM

Data and program memory use separate busses, which allows for concurrent access of these blocks.

Additional detailed information for FLASH program memory and Data EEPROM is provided in Section 5.0 and Section 6.0, respectively.

4.1 Program Memory Organization

A 21-bit program counter is capable of addressing the 2-Mbyte program memory space. Accessing a location between the physically implemented memory and the 2-Mbyte address will cause a read of all '0's (a NOP instruction).

The PIC18F252 and PIC18F452 each have 32 Kbytes of FLASH memory, while the PIC18F242 and PIC18F442 have 16 Kbytes of FLASH. This means that PIC18FX52 devices can store up to 16K of single word instructions, and PIC18FX42 devices can store up to 8K of single word instructions.

The RESET vector address is at 0000h and the interrupt vector addresses are at 0008h and 0018h.

Figure 4-1 shows the Program Memory Map for PIC18F242/442 devices and Figure 4-2 shows the Program Memory Map for PIC18F252/452 devices.

4.3 Fast Register Stack

A “fast interrupt return” option is available for interrupts. A Fast Register Stack is provided for the STATUS, WREG and BSR registers and are only one in depth. The stack is not readable or writable and is loaded with the current value of the corresponding register when the processor vectors for an interrupt. The values in the registers are then loaded back into the working registers, if the FAST RETURN instruction is used to return from the interrupt.

A low or high priority interrupt source will push values into the stack registers. If both low and high priority interrupts are enabled, the stack registers cannot be used reliably for low priority interrupts. If a high priority interrupt occurs while servicing a low priority interrupt, the stack register values stored by the low priority interrupt will be overwritten.

If high priority interrupts are not disabled during low priority interrupts, users must save the key registers in software during a low priority interrupt.

If no interrupts are used, the fast register stack can be used to restore the STATUS, WREG and BSR registers at the end of a subroutine call. To use the fast register stack for a subroutine call, a FAST CALL instruction must be executed.

Example 4-1 shows a source code example that uses the fast register stack.

EXAMPLE 4-1: FAST REGISTER STACK CODE EXAMPLE

```

CALL SUB1, FAST      ;STATUS, WREG, BSR
                    ;SAVED IN FAST REGISTER
                    ;STACK
    .
    .
SUB1
    .
    .
RETURN FAST         ;RESTORE VALUES SAVED
                    ;IN FAST REGISTER STACK
    
```

4.4 PCL, PCLATH and PCLATU

The program counter (PC) specifies the address of the instruction to fetch for execution. The PC is 21-bits wide. The low byte is called the PCL register. This register is readable and writable. The high byte is called the PCH register. This register contains the PC<15:8> bits and is not directly readable or writable. Updates to the PCH register may be performed through the PCLATH register. The upper byte is called PCU. This register contains the PC<20:16> bits and is not directly readable or writable. Updates to the PCU register may be performed through the PCLATU register.

The PC addresses bytes in the program memory. To prevent the PC from becoming misaligned with word instructions, the LSB of PCL is fixed to a value of '0'. The PC increments by 2 to address sequential instructions in the program memory.

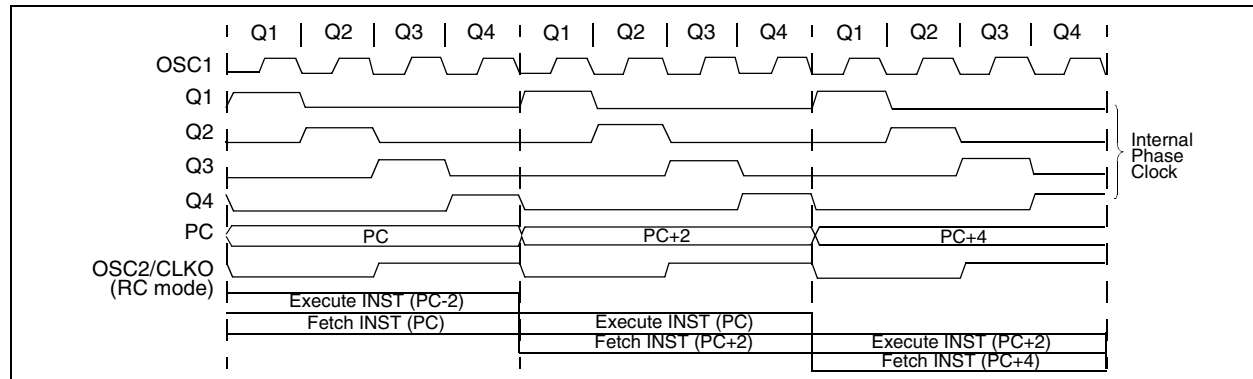
The CALL, RCALL, GOTO and program branch instructions write to the program counter directly. For these instructions, the contents of PCLATH and PCLATU are not transferred to the program counter.

The contents of PCLATH and PCLATU will be transferred to the program counter by an operation that writes PCL. Similarly, the upper two bytes of the program counter will be transferred to PCLATH and PCLATU by an operation that reads PCL. This is useful for computed offsets to the PC (see Section 4.8.1).

4.5 Clocking Scheme/Instruction Cycle

The clock input (from OSC1) is internally divided by four to generate four non-overlapping quadrature clocks, namely Q1, Q2, Q3 and Q4. Internally, the program counter (PC) is incremented every Q1, the instruction is fetched from the program memory and latched into the instruction register in Q4. The instruction is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow are shown in Figure 4-4.

FIGURE 4-4: CLOCK/INSTRUCTION CYCLE



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NOTES:

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FIGURE 9-2: BLOCK DIAGRAM OF RA4/T0CKI PIN

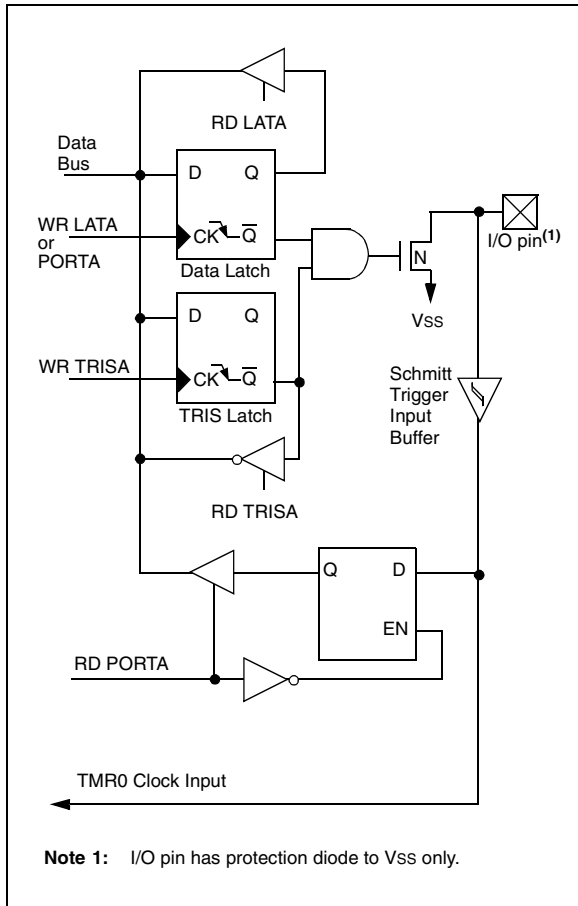
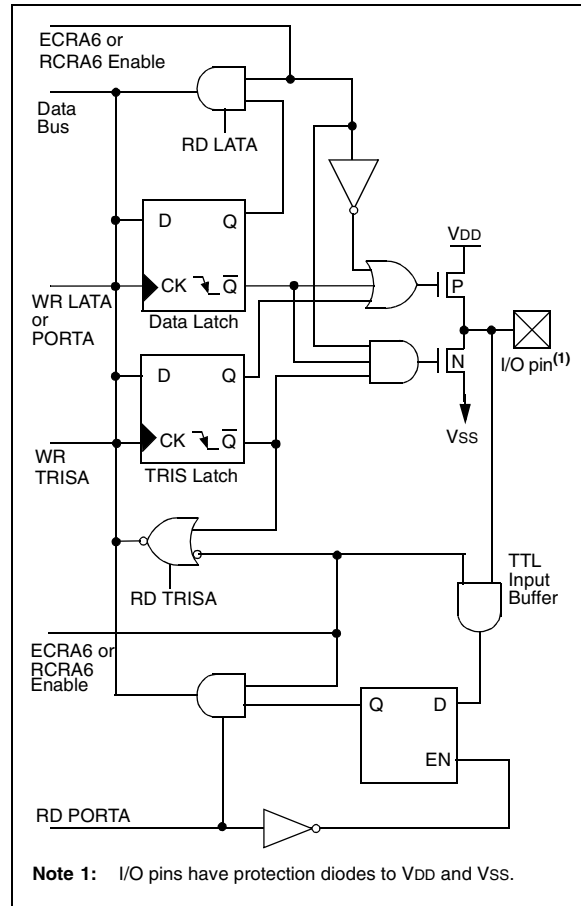


FIGURE 9-3: BLOCK DIAGRAM OF RA6 PIN



9.3 PORTC, TRISC and LATC Registers

PORTC is an 8-bit wide, bi-directional port. The corresponding Data Direction register is TRISC. Setting a TRISC bit (= 1) will make the corresponding PORTC pin an input (i.e., put the corresponding output driver in a Hi-Impedance mode). Clearing a TRISC bit (= 0) will make the corresponding PORTC pin an output (i.e., put the contents of the output latch on the selected pin).

The Data Latch register (LATC) is also memory mapped. Read-modify-write operations on the LATC register reads and writes the latched output value for PORTC.

PORTC is multiplexed with several peripheral functions (Table 9-5). PORTC pins have Schmitt Trigger input buffers.

When enabling peripheral functions, care should be taken in defining TRIS bits for each PORTC pin. Some peripherals override the TRIS bit to make a pin an output, while other peripherals override the TRIS bit to make a pin an input. The user should refer to the corresponding peripheral section for the correct TRIS bit settings.

Note: On a Power-on Reset, these pins are configured as digital inputs.

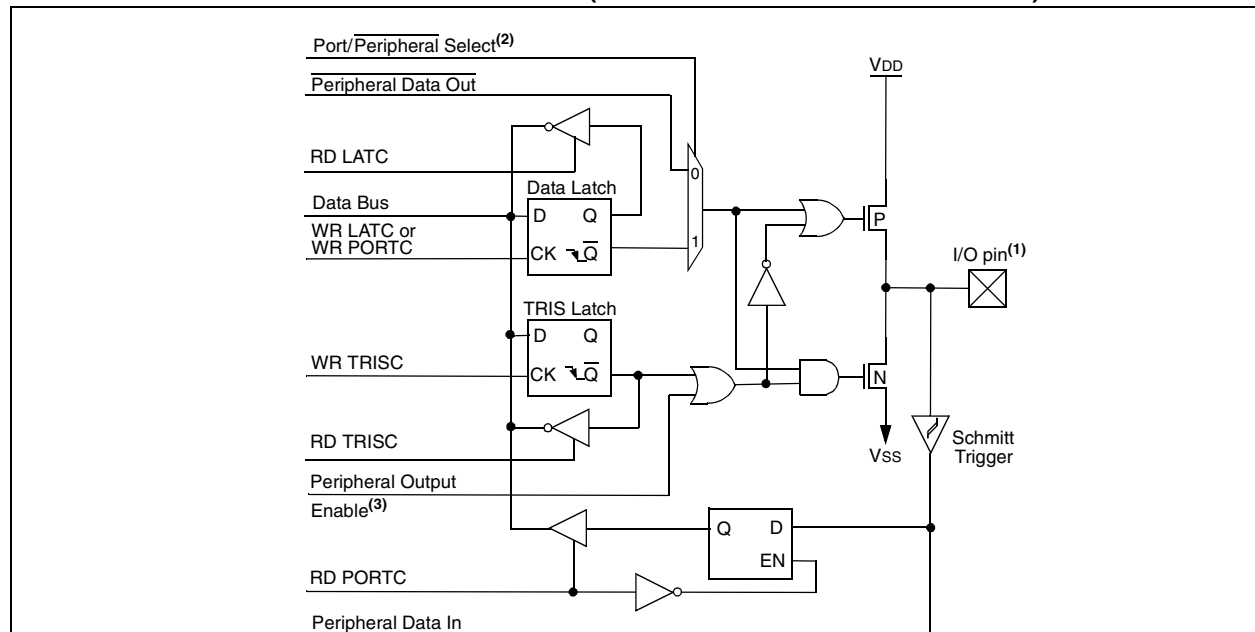
The pin override value is not loaded into the TRIS register. This allows read-modify-write of the TRIS register, without concern due to peripheral overrides.

RC1 is normally configured by configuration bit, CCP2MX, as the default peripheral pin of the CCP2 module (default/erased state, CCP2MX = '1').

EXAMPLE 9-3: INITIALIZING PORTC

```
CLRF   PORTC   ; Initialize PORTC by
                ; clearing output
                ; data latches
CLRF   LATC    ; Alternate method
                ; to clear output
                ; data latches
MOVLW 0xCF    ; Value used to
                ; initialize data
                ; direction
MOVWF  TRISC   ; Set RC<3:0> as inputs
                ; RC<5:4> as outputs
                ; RC<7:6> as inputs
```

FIGURE 9-7: PORTC BLOCK DIAGRAM (PERIPHERAL OUTPUT OVERRIDE)



- Note 1:** I/O pins have diode protection to VDD and VSS.
Note 2: Port/Peripheral Select signal selects between port data (input) and peripheral output.
Note 3: Peripheral Output Enable is only active if peripheral select is active.

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TABLE 11-2: REGISTERS ASSOCIATED WITH TIMER1 AS A TIMER/COUNTER

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on All Other RESETS
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x	0000 000u
PIR1	PSPIF ⁽¹⁾	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
PIE1	PSPIE ⁽¹⁾	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
IPR1	PSPIP ⁽¹⁾	ADIP	RCIP	TXIP	SSPIP	CCP1IP	TMR2IP	TMR1IP	0000 0000	0000 0000
TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
T1CON	RD16	—	T1CKPS1	T1CKPS0	T1OSCEN	T1SYNC	TMR1CS	TMR1ON	0-00 0000	u-uu uuuu

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by the Timer1 module.

Note 1: The PSPIF, PSPIE and PSPIP bits are reserved on the PIC18F2X2 devices; always maintain these bits clear.

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14.4 Compare Mode

In Compare mode, the 16-bit CCPR1 (CCPR2) register value is constantly compared against either the TMR1 register pair value, or the TMR3 register pair value. When a match occurs, the RC2/CCP1 (RC1/CCP2) pin is:

- driven High
- driven Low
- toggle output (High to Low or Low to High)
- remains unchanged

The action on the pin is based on the value of control bits CCP1M3:CCP1M0 (CCP2M3:CCP2M0). At the same time, interrupt flag bit CCP1IF (CCP2IF) is set.

14.4.1 CCP PIN CONFIGURATION

The user must configure the CCPx pin as an output by clearing the appropriate TRISC bit.

Note: Clearing the CCP1CON register will force the RC2/CCP1 compare output latch to the default low level. This is not the PORTC I/O data latch.

14.4.2 TIMER1/TIMER3 MODE SELECTION

Timer1 and/or Timer3 must be running in Timer mode or Synchronized Counter mode if the CCP module is using the compare feature. In Asynchronous Counter mode, the compare operation may not work.

14.4.3 SOFTWARE INTERRUPT MODE

When generate software interrupt is chosen, the CCP1 pin is not affected. Only a CCP interrupt is generated (if enabled).

14.4.4 SPECIAL EVENT TRIGGER

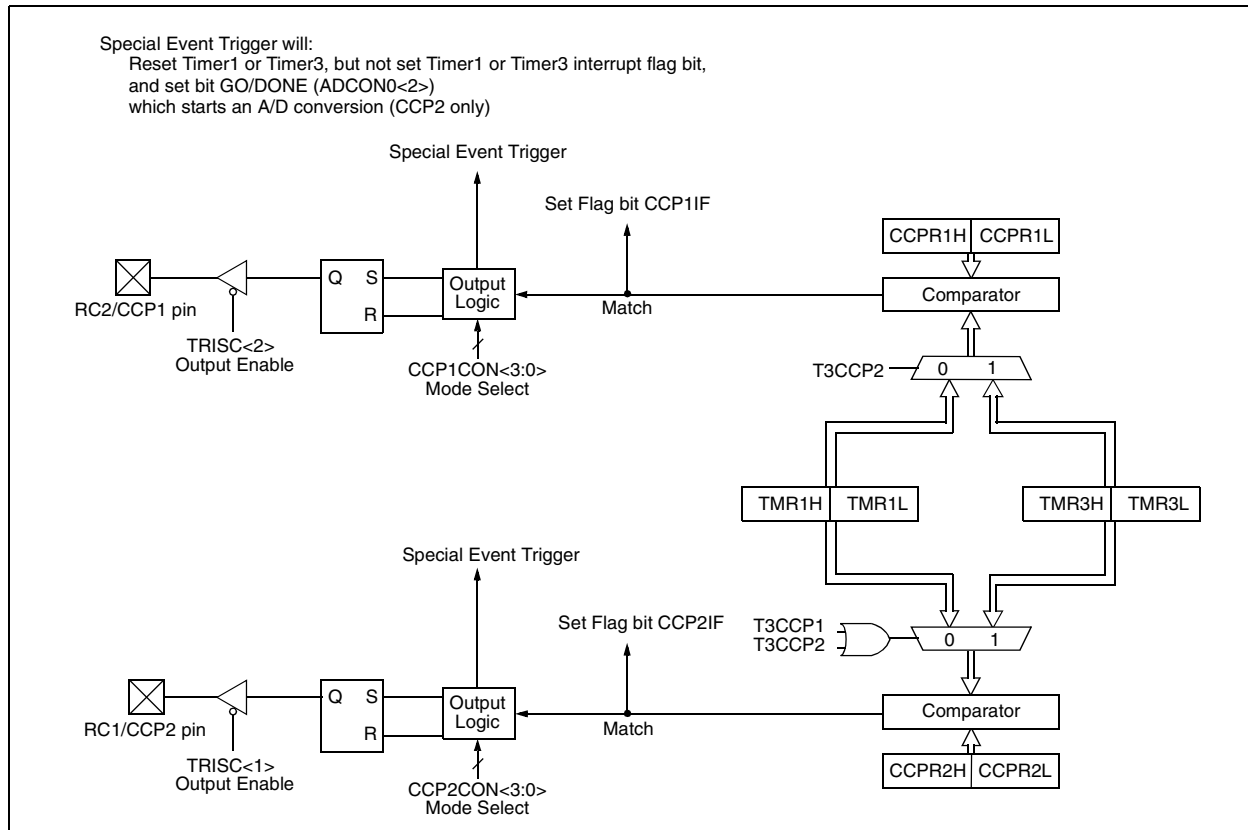
In this mode, an internal hardware trigger is generated, which may be used to initiate an action.

The special event trigger output of CCP1 resets the TMR1 register pair. This allows the CCPR1 register to effectively be a 16-bit programmable period register for Timer1.

The special trigger output of CCPx resets either the TMR1 or TMR3 register pair. Additionally, the CCP2 Special Event Trigger will start an A/D conversion if the A/D module is enabled.

Note: The special event trigger from the CCP2 module will not set the Timer1 or Timer3 interrupt flag bits.

FIGURE 14-2: COMPARE MODE OPERATION BLOCK DIAGRAM



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15.4.4 CLOCK STRETCHING

Both 7- and 10-bit Slave modes implement automatic clock stretching during a transmit sequence.

The SEN bit (SSPCON2<0>) allows clock stretching to be enabled during receives. Setting SEN will cause the SCL pin to be held low at the end of each data receive sequence.

15.4.4.1 Clock Stretching for 7-bit Slave Receive Mode (SEN = 1)

In 7-bit Slave Receive mode, on the falling edge of the ninth clock at the end of the ACK sequence, if the BF bit is set, the CKP bit in the SSPCON1 register is automatically cleared, forcing the SCL output to be held low. The CKP being cleared to '0' will assert the SCL line low. The CKP bit must be set in the user's ISR before reception is allowed to continue. By holding the SCL line low, the user has time to service the ISR and read the contents of the SSPBUF before the master device can initiate another receive sequence. This will prevent buffer overruns from occurring (see Figure 15-13).

Note 1: If the user reads the contents of the SSPBUF before the falling edge of the ninth clock, thus clearing the BF bit, the CKP bit will not be cleared and clock stretching will not occur.

2: The CKP bit can be set in software, regardless of the state of the BF bit. The user should be careful to clear the BF bit in the ISR before the next receive sequence, in order to prevent an overflow condition.

15.4.4.2 Clock Stretching for 10-bit Slave Receive Mode (SEN = 1)

In 10-bit Slave Receive mode, during the address sequence, clock stretching automatically takes place but CKP is not cleared. During this time, if the UA bit is set after the ninth clock, clock stretching is initiated. The UA bit is set after receiving the upper byte of the 10-bit address, and following the receive of the second byte of the 10-bit address with the R/W bit cleared to '0'. The release of the clock line occurs upon updating SSPADD. Clock stretching will occur on each data receive sequence as described in 7-bit mode.

Note: If the user polls the UA bit and clears it by updating the SSPADD register before the falling edge of the ninth clock occurs, and if the user hasn't cleared the BF bit by reading the SSPBUF register before that time, then the CKP bit will still NOT be asserted low. Clock stretching on the basis of the state of the BF bit only occurs during a data sequence, not an address sequence.

15.4.4.3 Clock Stretching for 7-bit Slave Transmit Mode

7-bit Slave Transmit mode implements clock stretching by clearing the CKP bit after the falling edge of the ninth clock, if the BF bit is clear. This occurs, regardless of the state of the SEN bit.

The user's ISR must set the CKP bit before transmission is allowed to continue. By holding the SCL line low, the user has time to service the ISR and load the contents of the SSPBUF before the master device can initiate another transmit sequence (see Figure 15-9).

Note 1: If the user loads the contents of SSPBUF, setting the BF bit before the falling edge of the ninth clock, the CKP bit will not be cleared and clock stretching will not occur.

2: The CKP bit can be set in software, regardless of the state of the BF bit.

15.4.4.4 Clock Stretching for 10-bit Slave Transmit Mode

In 10-bit Slave Transmit mode, clock stretching is controlled during the first two address sequences by the state of the UA bit, just as it is in 10-bit Slave Receive mode. The first two addresses are followed by a third address sequence, which contains the high order bits of the 10-bit address and the R/W bit set to '1'. After the third address sequence is performed, the UA bit is not set, the module is now configured in Transmit mode, and clock stretching is controlled by the BF flag, as in 7-bit Slave Transmit mode (see Figure 15-11).

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15.4.12 ACKNOWLEDGE SEQUENCE TIMING

An Acknowledge sequence is enabled by setting the Acknowledge sequence enable bit, ACKEN (SSPCON2<4>). When this bit is set, the SCL pin is pulled low and the contents of the Acknowledge data bit are presented on the SDA pin. If the user wishes to generate an Acknowledge, then the ACKDT bit should be cleared. If not, the user should set the ACKDT bit before starting an Acknowledge sequence. The baud rate generator then counts for one rollover period (TBRG) and the SCL pin is de-asserted (pulled high). When the SCL pin is sampled high (clock arbitration), the baud rate generator counts for TBRG. The SCL pin is then pulled low. Following this, the ACKEN bit is automatically cleared, the baud rate generator is turned off and the MSSP module then goes into IDLE mode (Figure 15-23).

15.4.12.1 WCOL Status Flag

If the user writes the SSPBUF when an Acknowledge sequence is in progress, then WCOL is set and the contents of the buffer are unchanged (the write doesn't occur).

15.4.13 STOP CONDITION TIMING

A STOP bit is asserted on the SDA pin at the end of a receive/transmit by setting the STOP sequence enable bit, PEN (SSPCON2<2>). At the end of a receive/transmit the SCL line is held low after the falling edge of the ninth clock. When the PEN bit is set, the master will assert the SDA line low. When the SDA line is sampled low, the baud rate generator is reloaded and counts down to 0. When the baud rate generator times out, the SCL pin will be brought high, and one TBRG (baud rate generator rollover count) later, the SDA pin will be de-asserted. When the SDA pin is sampled high while SCL is high, the P bit (SSPSTAT<4>) is set. A TBRG later, the PEN bit is cleared and the SSPIF bit is set (Figure 15-24).

15.4.13.1 WCOL Status Flag

If the user writes the SSPBUF when a STOP sequence is in progress, then the WCOL bit is set and the contents of the buffer are unchanged (the write doesn't occur).

FIGURE 15-23: ACKNOWLEDGE SEQUENCE WAVEFORM

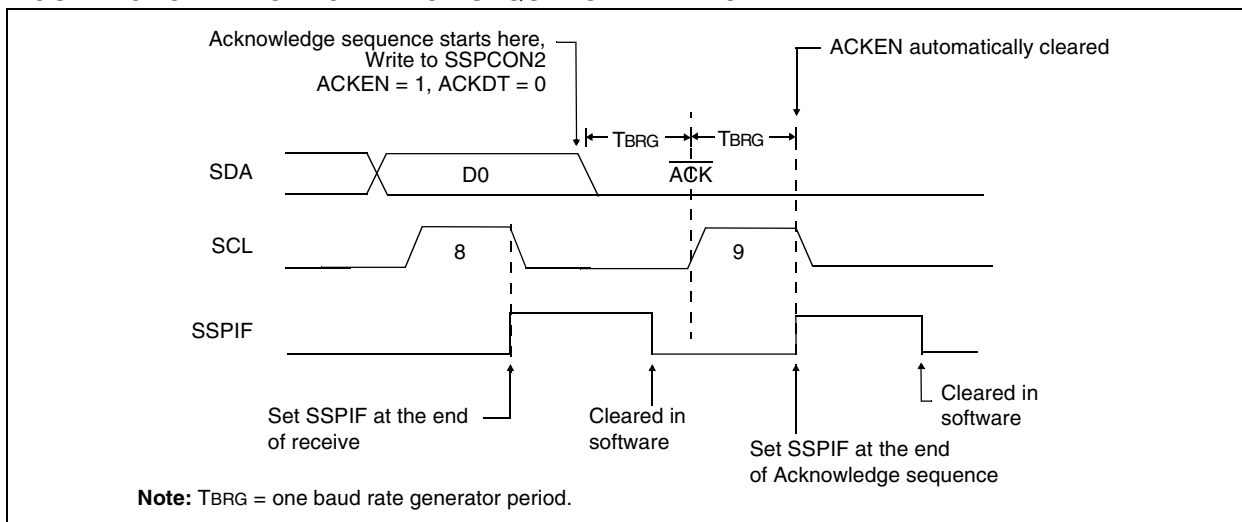
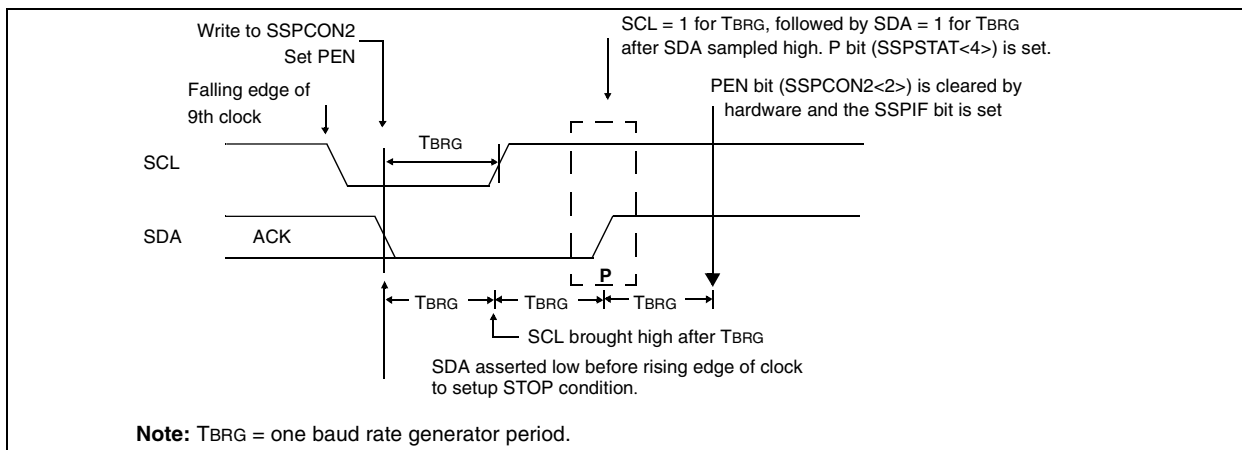
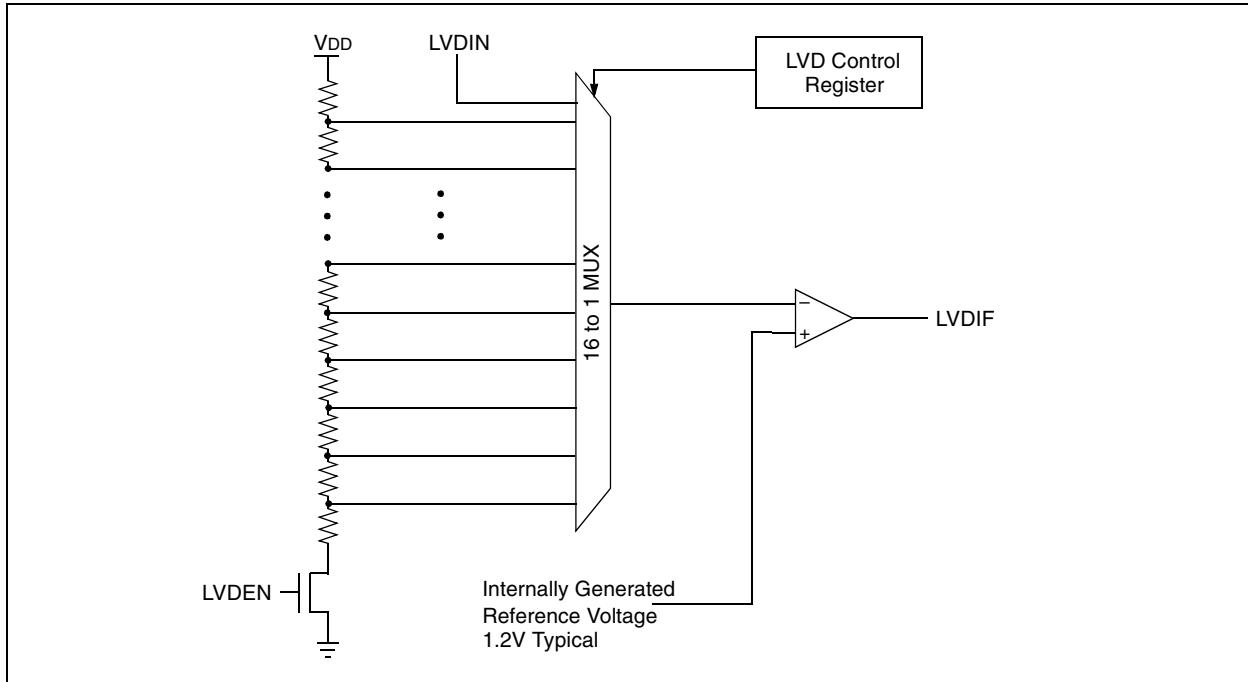


FIGURE 15-24: STOP CONDITION RECEIVE OR TRANSMIT MODE



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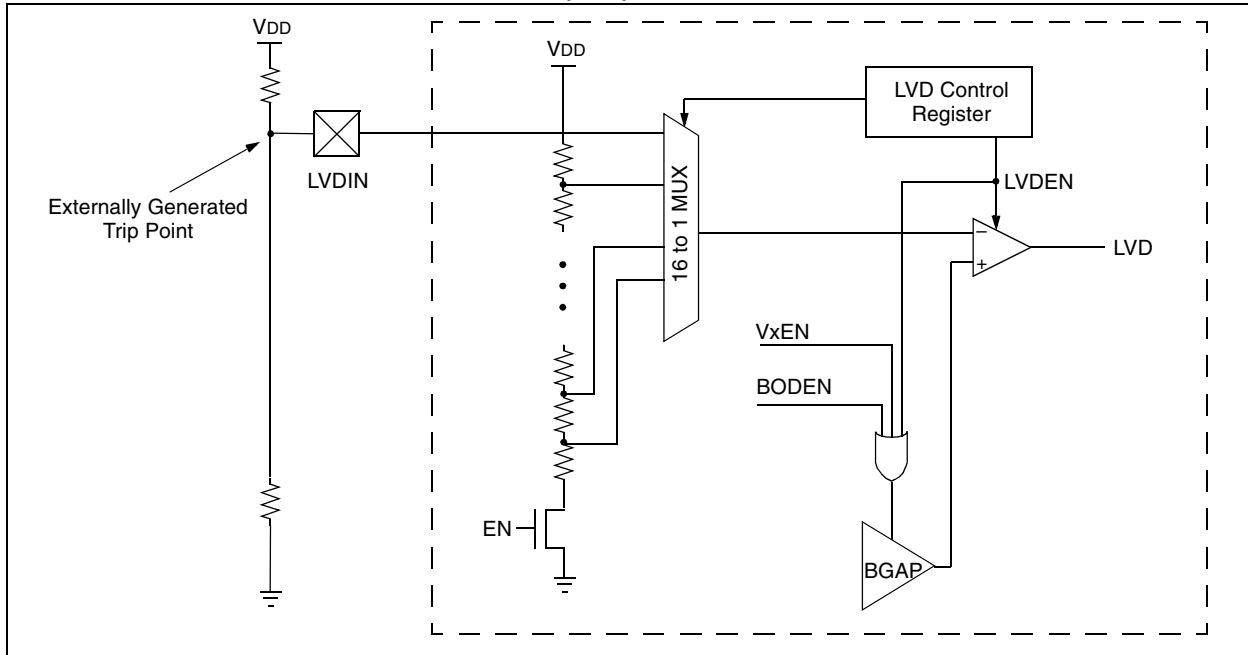
FIGURE 18-2: LOW VOLTAGE DETECT (LVD) BLOCK DIAGRAM



The LVD module has an additional feature that allows the user to supply the trip voltage to the module from an external source. This mode is enabled when bits LVDL3:LVDL0 are set to 1111. In this state, the comparator input is multiplexed from the external input pin,

LVDIN (Figure 18-3). This gives users flexibility, because it allows them to configure the Low Voltage Detect interrupt to occur at any voltage in the valid operating range.

FIGURE 18-3: LOW VOLTAGE DETECT (LVD) WITH EXTERNAL INPUT BLOCK DIAGRAM



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REGISTER 19-4: CONFIGURATION REGISTER 3 HIGH (CONFIG3H: BYTE ADDRESS 300005h)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/P-1
—	—	—	—	—	—	—	CCP2MX
bit 7							bit 0

- bit 7-1 **Unimplemented:** Read as '0'
- bit 0 **CCP2MX:** CCP2 Mux bit
 - 1 = CCP2 input/output is multiplexed with RC1
 - 0 = CCP2 input/output is multiplexed with RB3

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '0'
- n = Value when device is unprogrammed	u = Unchanged from programmed state	

REGISTER 19-5: CONFIGURATION REGISTER 4 LOW (CONFIG4L: BYTE ADDRESS 300006h)

R/P-1	U-0	U-0	U-0	U-0	R/P-1	U-0	R/P-1
<u>BKBUG</u>	—	—	—	—	LVP	—	STVREN
bit 7						bit 0	

- bit 7 **DEBUG:** Background Debugger Enable bit
 - 1 = Background Debugger disabled. RB6 and RB7 configured as general purpose I/O pins.
 - 0 = Background Debugger enabled. RB6 and RB7 are dedicated to In-Circuit Debug.
- bit 6-3 **Unimplemented:** Read as '0'
- bit 2 **LVP:** Low Voltage ICSP Enable bit
 - 1 = Low Voltage ICSP enabled
 - 0 = Low Voltage ICSP disabled
- bit 1 **Unimplemented:** Read as '0'
- bit 0 **STVREN:** Stack Full/Underflow Reset Enable bit
 - 1 = Stack Full/Underflow will cause RESET
 - 0 = Stack Full/Underflow will not cause RESET

Legend:		
R = Readable bit	C = Clearable bit	U = Unimplemented bit, read as '0'
- n = Value when device is unprogrammed	u = Unchanged from programmed state	

REGISTER 19-6: CONFIGURATION REGISTER 5 LOW (CONFIG5L: BYTE ADDRESS 300008h)

U-0	U-0	U-0	U-0	R/C-1	R/C-1	R/C-1	R/C-1
—	—	—	—	CP3 ⁽¹⁾	CP2 ⁽¹⁾	CP1	CP0

bit 7

bit 0

bit 7-4 **Unimplemented:** Read as '0'

bit 3 **CP3:** Code Protection bit⁽¹⁾

1 = Block 3 (006000-007FFFh) not code protected

0 = Block 3 (006000-007FFFh) code protected

bit 2 **CP2:** Code Protection bit⁽¹⁾

1 = Block 2 (004000-005FFFh) not code protected

0 = Block 2 (004000-005FFFh) code protected

bit 1 **CP1:** Code Protection bit

1 = Block 1 (002000-003FFFh) not code protected

0 = Block 1 (002000-003FFFh) code protected

bit 0 **CP0:** Code Protection bit

1 = Block 0 (000200-001FFFh) not code protected

0 = Block 0 (000200-001FFFh) code protected

Note 1: Unimplemented in PIC18FX42 devices; maintain this bit set.

Legend:

R = Readable bit

C = Clearable bit

U = Unimplemented bit, read as '0'

- n = Value when device is unprogrammed

u = Unchanged from programmed state

REGISTER 19-7: CONFIGURATION REGISTER 5 HIGH (CONFIG5H: BYTE ADDRESS 300009h)

R/C-1	R/C-1	U-0	U-0	U-0	U-0	U-0	U-0
CPD	CPB	—	—	—	—	—	—

bit 7

bit 0

bit 7 **CPD:** Data EEPROM Code Protection bit

1 = Data EEPROM not code protected

0 = Data EEPROM code protected

bit 6 **CPB:** Boot Block Code Protection bit

1 = Boot Block (000000-0001FFh) not code protected

0 = Boot Block (000000-0001FFh) code protected

bit 5-0 **Unimplemented:** Read as '0'

Legend:

R = Readable bit

C = Clearable bit

U = Unimplemented bit, read as '0'

- n = Value when device is unprogrammed

u = Unchanged from programmed state

MOVLW Move literal to W

Syntax: [*label*] MOVLW *k*

Operands: $0 \leq k \leq 255$

Operation: $k \rightarrow W$

Status Affected: None

Encoding:

0000	1110	kkkk	kkkk
------	------	------	------

Description: The eight-bit literal '*k*' is loaded into W.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal ' <i>k</i> '	Process Data	Write to W

Example: MOVLW 0x5A

After Instruction

W = 0x5A

MOVWF Move W to f

Syntax: [*label*] MOVWF *f* [,a]

Operands: $0 \leq f \leq 255$
 $a \in [0,1]$

Operation: $(W) \rightarrow f$

Status Affected: None

Encoding:

0110	111a	ffff	ffff
------	------	------	------

Description: Move data from W to register '*f*'. Location '*f*' can be anywhere in the 256 byte bank. If '*a*' is 0, the Access Bank will be selected, overriding the BSR value. If '*a*' = 1, then the bank will be selected as per the BSR value (default).

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register ' <i>f</i> '	Process Data	Write register ' <i>f</i> '

Example: MOVWF REG, 0

Before Instruction

W = 0x4F
REG = 0xFF

After Instruction

W = 0x4F
REG = 0x4F

PIC18FXX2

22.1 DC Characteristics: PIC18FXX2 (Industrial, Extended) PIC18LFXX2 (Industrial) (Continued)

PIC18LFXX2 (Industrial)		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial							
PIC18FXX2 (Industrial, Extended)		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended							
Param No.	Symbol	Characteristic	Min	Typ	Max	Units	Conditions		
D010	IDD	Supply Current^(2,4)							
		PIC18LFXX2	—	.5	1	mA	XT osc configuration VDD = 2.0V, +25°C, FOSC = 4 MHz		
			—	.5	1.25	mA	VDD = 2.0V, -40°C to +85°C, FOSC = 4 MHz		
			—	1.2	2	mA	VDD = 4.2V, -40°C to +85°C, FOSC = 4 MHz		
		PIC18FXX2	—	.3	1	mA	RC osc configuration VDD = 2.0V, +25°C, FOSC = 4 MHz		
			—	.3	1	mA	VDD = 2.0V, -40°C to +85°C, FOSC = 4 MHz		
			—	1.5	3	mA	VDD = 4.2V, -40°C to +85°C, FOSC = 4 MHz		
		D010		PIC18LFXX2	—	.3	1	mA	RCIO osc configuration VDD = 2.0V, +25°C, FOSC = 4 MHz
					—	.3	1	mA	VDD = 2.0V, -40°C to +85°C, FOSC = 4 MHz
—	.75				3	mA	VDD = 4.2V, -40°C to +85°C, FOSC = 4 MHz		
PIC18FXX2	—			1.2	1.5	mA	XT osc configuration VDD = 4.2V, +25°C, FOSC = 4 MHz		
	—			1.2	2	mA	VDD = 4.2V, -40°C to +85°C, FOSC = 4 MHz		
	—			1.2	3	mA	VDD = 4.2V, -40°C to +125°C, FOSC = 4 MHz		
	—			1.5	3	mA	RC osc configuration VDD = 4.2V, +25°C, FOSC = 4 MHz		
	—			1.5	4	mA	VDD = 4.2V, -40°C to +85°C, FOSC = 4 MHz		
	—			1.6	4	mA	VDD = 4.2V, -40°C to +125°C, FOSC = 4 MHz		
PIC18FXX2	—	.75	2	mA	RCIO osc configuration VDD = 4.2V, +25°C, FOSC = 4 MHz				
	—	.75	3	mA	VDD = 4.2V, -40°C to +85°C, FOSC = 4 MHz				
	—	.8	3	mA	VDD = 4.2V, -40°C to +125°C, FOSC = 4 MHz				
D010A		PIC18LFXX2	—	14	30	μA	LP osc, FOSC = 32 kHz, WDT disabled VDD = 2.0V, -40°C to +85°C		
D010A		PIC18FXX2	—	40	70	μA	LP osc, FOSC = 32 kHz, WDT disabled VDD = 4.2V, -40°C to +85°C		
			—	50	100	μA	VDD = 4.2V, -40°C to +125°C		

Legend: Shading of rows is to assist in readability of the table.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode, or during a device RESET, without losing RAM data.

Note 2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

The test conditions for all IDD measurements in active Operation mode are:

OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD

MCLR = VDD; WDT enabled/disabled as specified.

Note 3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS, and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR,...).

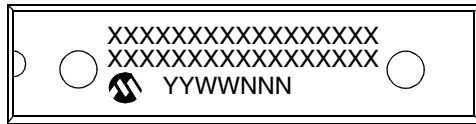
Note 4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula $I_r = V_{DD}/2R_{EXT}$ (mA) with REXT in kOhm.

Note 5: The LVD and BOR modules share a large portion of circuitry. The ΔI_{BOR} and ΔI_{LVD} currents are not additive. Once one of these modules is enabled, the other may also be enabled without further penalty.

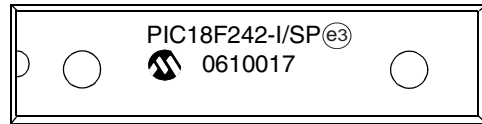
24.0 PACKAGING INFORMATION

24.1 Package Marking Information

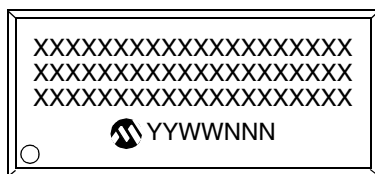
28-Lead SPDIP



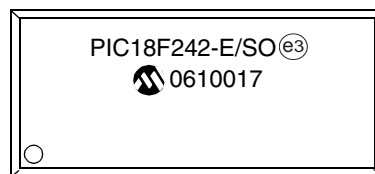
Example



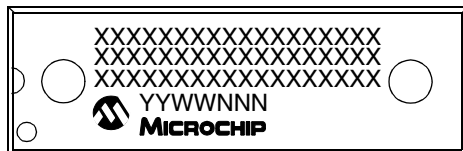
28-Lead SOIC



Example



40-Lead PDIP



Example



Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

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